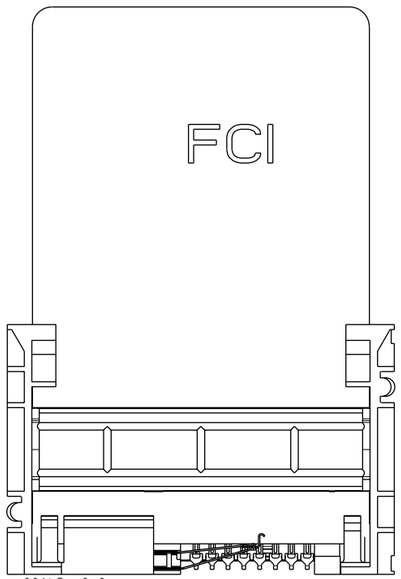
7334L2622F13LF

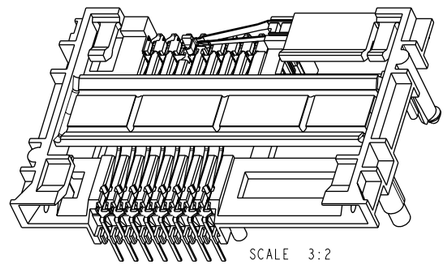
Lead Free Version (Optional)

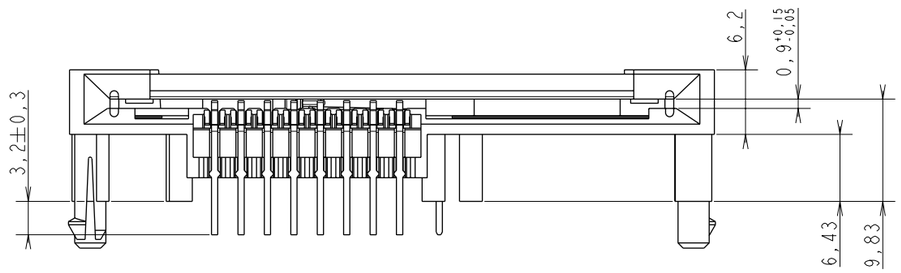
Durability
0: 2500 Mating Cycles
2: 10000 Mating Cycles
5: 100000 Mating Cycles

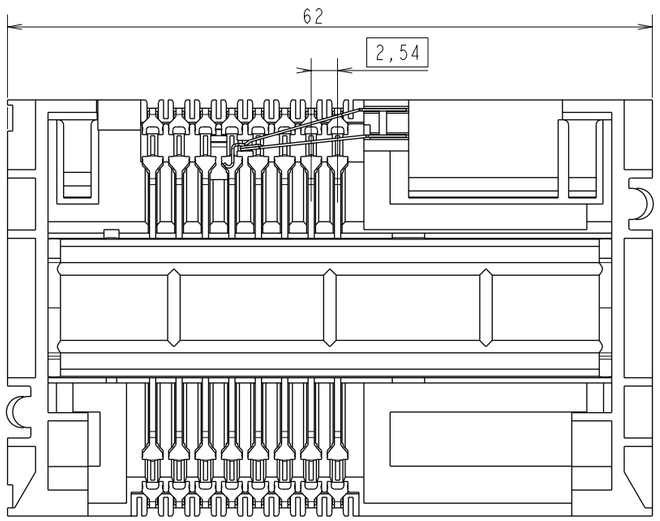
Number of contacts :
2: 8 contacts ISO
3: 16 contacts ISO + AFNOR

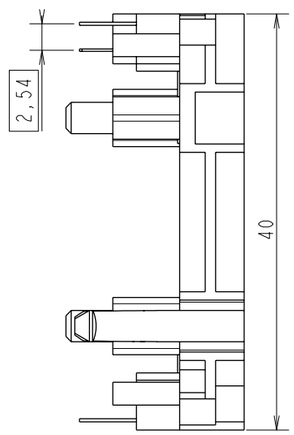


SCALE 3:2


SCALE 3:2







General Tolerances:± 0.2 mm

GENERAL:
This L26 connector uses a "sliding" contact technology suitable for most applications.
It has been designed for easy mounting on the PCB.

ELECTRICAL PROPERTIES:
Insulation resistance : 5000 MΩ min
Dielectric withstanding : 750 Vrms min
Current carrying capacity : 10µA min. 1A max
Contact resistance : 100mΩ max
Card sensor type : Normally closed

MECHANICAL PROPERTIES:
Contact Normal force : 0.6 N max (EMV Standard)
Insertion force : 10 N max
Extraction force : 1 N min

MATERIAL:
Housing : Thermoplastic, Colour Black, Rated UL94V0
Contacts and switch : Copper Alloy
Plating : Gold over Nickel on contact area
Matte Tin over Nickel on solder tails
Bare edge allowed

ENVIRONMENT:
Operating temperature: -20°C / +70°C
Storage temperature: -40°C / +85°C
Printed Circuit Board thickness : 1.6mm

REFERENCE DOCUMENTS:
Product specification VGN 11596
Packaging Specification VGN 11619

LEAD FREE VERSION:

"This product meets European Union Directives and other country regulations as described in GS-22-008"

The housing will withstand exposure to 260°C peak temperature for 10seconds in a wave solder application with a 1.6mm minimum thick circuit board.
Use protective adhesive tape (Kapton orTeflon) or protective metallic devices on the areas which are directly exposed to wave soldering as it is used in classical leaded wave soldering

EUROPEAN PROJECTION

ltr	ecn no	dr	date
A	F20307	DLE	2002/04/30
B	LS 3053	JTA	2003/05/13
C	105-0071	DTK	2005/05/10
D	106-0084	SSC	2006/06/21
E	106-0183	SSC	2006/10/05
F	109-0057	SSC	2009/04/15
-	-	-	-

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surface - ISO 1302 | tolerance std ISO 406 ISO 1101 | projection | mm

TOLERANCES UNLESS OTHERWISE SPECIFIED

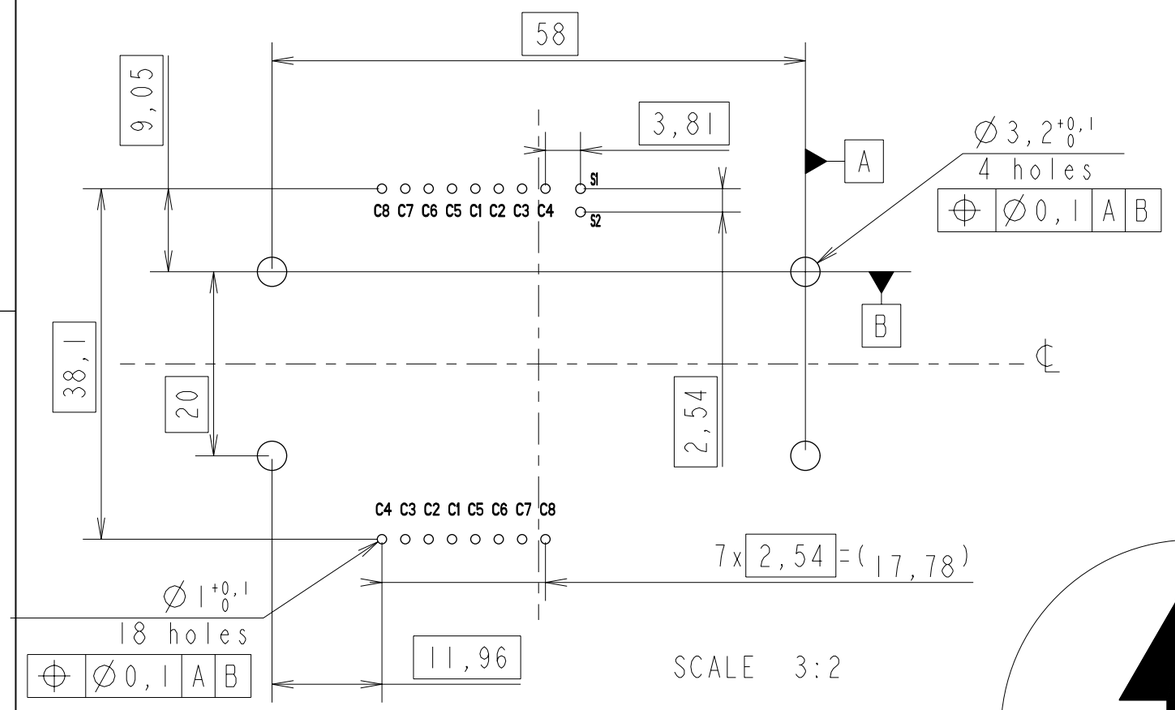
Dr	N.TWINCY	2002/04/30	ANGULAR	LINEAR	0.X ±	size A2
Eng	F TISSERAND	2002/04/30			0.XX ±	Scale 5:2
Chr	RAMESH.P.K	2009/04/15	0° ±°		0.XXX ±	ECN 109-0057
Appr	S.S.CHERIAN	2009/04/15	Product family SMART CARDS			Spec ref SEE NOTES

title: L26 TYPE F13 -- | dwg no: VJW_54825 | Rev. F | catalog no: See Table | - | sheet 1 of 2

REV F - 2006-04-17

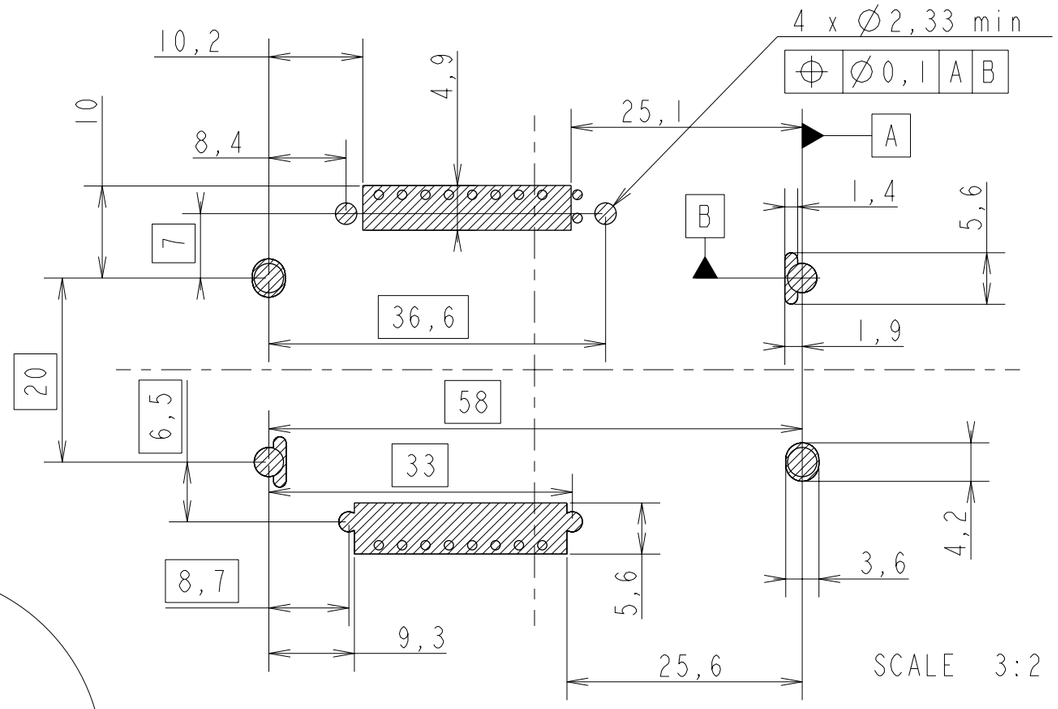
PDM: Rev:F STATUS: Released Printed: Apr 24, 2009

RECOMMENDED PCB LAYOUT CONTACT CONFIGURATION : ISO & AFNOR (CONNECTOR SIDE)



SCALE 3:2

STANDARD LAYOUT FOR 'KEEP OUT ZONE' (Connector Side)

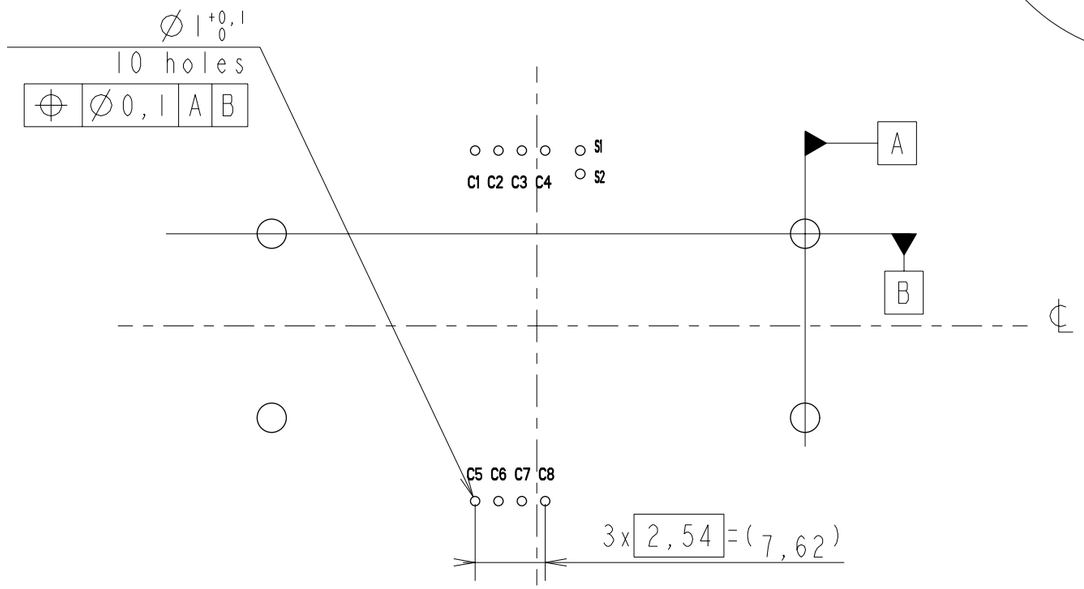


SCALE 3:2

Hatching area might be free of components
Maximum free space outside of these zones = 6.4 mm

CARD INSERTION

RECOMMENDED PCB LAYOUT CONTACT CONFIGURATION : ISO (CONNECTOR SIDE)



SCALE 3:2

REV F - 2006-04-17

EUROPEAN PROJECTION

www.fciconnect.com			surface ISO 1302		tolerance std ISO 406 ISO 1101		projection	mm
			TOLERANCES UNLESS OTHERWISE SPECIFIED					
Dr	N.TWINCY	2002/04/30	ANGULAR	LINEAR	0.X	±	size A3	Scale 3:2
Eng	F TISSERAND	2002/04/30			0.XX	±		
Chr	RAMESH.P.K	2009/04/15	0° ±°		0.XXX	±	ECN	109-0057
Appr	S.S.CHERIAN	2009/04/15	Product family SMART CARDS				Spec ref	SEE NOTES
FCI	title L26 TYPE F13 --				dwg no VJW_54825		Rev. F	
	catalog no See Table				-		sheet 2 of 2	

PDM: Rev:F STATUS: Released Printed: Apr 24, 2009